

# PATENT ASSIGNMENT

Electronic Version v1.1  
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
OEG-TEG, LLC	03/19/2010
<b>RECEIVING PARTY DATA</b>	
Name:	OEM Group Inc.
Street Address:	2120 W. Guadalupe Road
City:	Gilbert
State/Country:	ARIZONA
Postal Code:	85233
<b>PROPERTY NUMBERS Total: 3</b>	
Property Type	Number
Application Number:	12203022
Application Number:	10371862
Application Number:	12552664
<b>CORRESPONDENCE DATA</b>	
Fax Number:	(415)362-2928
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	4153623800
Email:	officeactions@fdml.com
Correspondent Name:	Fliesler Meyer LLP
Address Line 1:	650 California Street, 14th Floor
Address Line 4:	San Francisco, CALIFORNIA 94108
ATTORNEY DOCKET NUMBER:	OEMG-00300US0
NAME OF SUBMITTER:	Sheldon R. Meyer
Total Attachments: 22 source=OEMGAssignmentWithExhibitsEfile#page1.tif source=OEMGAssignmentWithExhibitsEfile#page2.tif	

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**PATENT**  
**REEL: 024551 FRAME: 0016**

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## FIRST AMENDMENT TO ASSET PURCHASE AGREEMENT

THIS FIRST AMENDMENT TO ASSET PURCHASE AGREEMENT (this "**Amendment**") is made and entered into as of April \_\_, 2010, and amends that certain Asset Purchase Agreement, dated as of March 19, 2010 (the "**Original Agreement**"), by and among Tegal Corporation, a Delaware corporation ("**Tegal**"), Sputtered Films, Inc., a California corporation and a wholly-owned subsidiary of Tegal ("**SFI**" and together with Tegal, "**Sellers**"), OEM Group Inc., an Arizona corporation ("**OEM Group**"), and OEG-TEG, LLC, an Arizona limited liability company ("**Purchaser**") (each Seller, OEM Group and Purchaser, a "**Party**" and collectively, the "**Parties**"). All capitalized terms which are used but not otherwise defined herein shall have the meanings specified to such terms in the Original Agreement.

### WITNESSETH:

**WHEREAS**, Sellers, OEM Group and Purchaser are parties to the Original Agreement;

**WHEREAS**, pursuant to Section 9.4 of the Original Agreement, the Parties may amend the Original Agreement by a writing signed by each of the Parties; and

**WHEREAS**, the Parties desire to amend the Original Agreement as set forth below.

**NOW, THEREFORE**, in consideration of the premises and of the mutual covenants and agreements contained herein and for other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Parties, intending to be legally bound, hereby agree as follows:

1.1 Item 1 to Schedule 2.1.1(e). The Transferred Issued Patents.pdf referenced in Item 1 of Schedule 2.1.1(e) to the Original Agreement is hereby amended and replaced in its entirety by substituting therefor the Transferred Issued Patents.pdf attached hereto as Annex 1.

1.2 Item 2 to Schedule 2.1.1(e). The Transferred Pending and Apps.pdf referenced in Item 2 of Schedule 2.1.1(e) to the Original Agreement is hereby amended and replaced in its entirety by substituting therefor the Transferred Pending and Apps.pdf attached hereto as Annex 2.

1.3 Exhibit A to Exhibit G. Exhibit A to Exhibit G (the "**Patent Assignment Agreement**") of the Original Agreement is hereby amended and replaced in its entirety by substituting therefor the Exhibit A to the Patent Assignment Agreement attached hereto as Annex 3.

1.4 Continued Force and Effect. Except as expressly provided herein, this Amendment shall not constitute an amendment, modification or waiver of any provision of the Original Agreement or any rights or obligations of any Person under or in respect of the Original

Agreement. Except as expressly amended herein, the provisions of the Original Agreement are and shall remain in full force and effect and are hereby ratified and confirmed. On and after the date hereof, each reference in the Original Agreement to "this Agreement" or the words "hereunder", "hereof", "herein" or words of similar import referring to the Original Agreement, shall mean and be a reference to the Original Agreement, as amended by this Amendment. This Amendment shall be subject to, shall form a part of, and shall be governed by, the terms and conditions set forth in the Original Agreement, as amended by this Amendment.

1.5 Governing Law. This Amendment shall be governed by and interpreted and enforced in accordance with the laws of the State of California, without regard to the conflicts of laws rules of such state. The rights and obligations of the parties under this Amendment shall not be governed by the provisions of the 1980 United Nations Convention on Contracts for the International Sale of Goods or the United Nations Convention on the Limitation Period in the International Sale of Goods, as amended.

1.6 Counterparts. This Amendment may be executed in any number of counterparts and any Party hereto may execute any such counterpart, each of which when executed and delivered shall be deemed to be an original and all of which counterparts taken together shall constitute but one and the same instrument. This Amendment shall become binding when one or more counterparts taken together shall have been executed and delivered by the parties. It shall not be necessary in making proof of this Amendment or any counterpart hereof to produce or account for any of the other counterparts.

1.8 Severability. Any provision of this Amendment which is invalid or unenforceable in any jurisdiction shall be ineffective to the extent of such invalidity or unenforceability without invalidating or rendering unenforceable the remaining provisions hereof, and any such invalidity or unenforceability in any jurisdiction shall not invalidate or render unenforceable such provision in any other jurisdiction.

1.9 Headings. All section headings contained in this Amendment are for convenience of reference only, do not form a part of this Amendment and shall not affect in any way the meaning or interpretation of this Amendment.

1.10 Amendments and Waivers. No amendment of any provision of this Amendment shall be valid unless the same shall be in writing and signed by each of the Parties.

[Signature page follows]

IN WITNESS WHEREOF, the Parties hereto have duly executed this Amendment as of the day and year first above written.

**TEGAL CORPORATION**

By: \_\_\_\_\_

Name: Thomas R. Mika

Title: President and Chief Executive Officer

**SPUTTERED FILMS, INC.**

By: \_\_\_\_\_

Name: Thomas R. Mika

Title: President and Chief Executive Officer

**OEG-TEG, LLC**

By: Wayne M. Jeveli

Name: Wayne Jeveli

Title: Manager

**OEM GROUP, INC.**

By: Wayne M. Jeveli

Name: Wayne Jeveli

Title: President

[SIGNATURE PAGE TO FIRST AMENDMENT TO ASSET PURCHASE AGREEMENT]

**ANNEX 1**

**TRANSFERRED ISSUED PATENTS.PDF OF ITEM 1 TO SCHEDULE 2.1.1(E) TO  
ASSET PURCHASE AGREEMENT**

(see attached)

**ANNEX 2**

**TRANSFERRED PENDING AND APPS.PDF OF ITEM 2 TO SCHEDULE 2.1.1(E) TO  
ASSET PURCHASE AGREEMENT**

(see attached)

**ANNEX 3**

**EXHIBIT A TO EXHIBIT G (PATENT ASSIGNMENT AGREEMENT) TO  
ASSET PURCHASE AGREEMENT  
(see attached)**



## ACKNOWLEDGMENT

THIS ACKNOWLEDGMENT (this "Acknowledgment") is made and entered into as of this \_\_\_ day of April, 2010 by and among Tegal Corporation, a Delaware corporation ("Tegal"), Sputtered Films, Inc., a California corporation (together with Tegal, "Assignors") and OEG-TEG, LLC, an Arizona limited liability corporation ("Assignee")

WHEREAS, the Assignors and Assignee entered into that certain Patent Assignment dated as of March 19, 2010 (the "Patent Assignment").

WHEREAS, due to clerical error, an incorrect Exhibit A was previously attached to the Patent Assignment.

WHEREAS, the parties wish to clarify that the attached Exhibit A is the correct and complete Exhibit A to the Patent Assignment.

NOW THEREFORE, the undersigned hereby acknowledge and agree as follows:

1. The attached Exhibit A is the correct and complete Exhibit A to the Patent Assignment.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, Assignors have caused this Acknowledgment to be executed by their duly authorized representatives as of the day and year first above written.

**TEGAL CORPORATION**

\_\_\_\_\_  
Name: Thomas R. Mika

Title: President and Chief Executive Officer

**SPUTTERED FILMS, INC.**

\_\_\_\_\_  
Name: Thomas R. Mika

Title: President and Chief Executive Officer

**ACKNOWLEDGEMENT:**

STATE OF CALIFORNIA       )  
                                      ) SS:  
COUNTY OF                    )

On \_\_\_\_\_ before me \_\_\_\_\_, personally appeared \_\_\_\_\_ who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature \_\_\_\_\_

(Seal)

**SIGNATURE PAGE TO ACKNOWLEDGMENT**

**PATENT**  
**REEL: 024551 FRAME: 0025**

IN WITNESS WHEREOF, Assignee has caused this Acknowledgment to be executed by its duly authorized representatives as of the day and year first above written.

OEG-TEG, LLC

Wayne M. Jeveli

Name: Wayne Jeveli

Title: Manager

ACKNOWLEDGEMENT:

STATE OF <sup>ARIZONA</sup> ~~CALIFORNIA~~ )

COUNTY OF MARICOPA )

) SS:

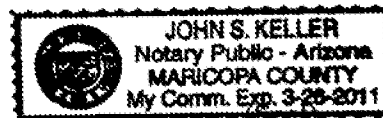
On MAY 14<sup>TH</sup> before me John S. Keller personally appeared \_\_\_\_\_ who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of <sup>ARIZONA</sup> ~~California~~ that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature

John S. Keller



SIGNATURE PAGE TO ACKNOWLEDGMENT

PATENT  
REEL: 024551 FRAME: 0026

## ACKNOWLEDGMENT

THIS ACKNOWLEDGMENT (this "Acknowledgment") is made and entered into as of this \_\_\_ day of April, 2010 by and among Tegal Corporation, a Delaware corporation ("Tegal"), Sputtered Films, Inc., a California corporation (together with Tegal, "Assignors") and OEG-TEG, LLC, an Arizona limited liability corporation ("Assignee")

WHEREAS, the Assignors and Assignee entered into that certain Patent Assignment dated as of March 19, 2010 (the "Patent Assignment").

WHEREAS, due to clerical error, an incorrect Exhibit A was previously attached to the Patent Assignment.

WHEREAS, the parties wish to clarify that the attached Exhibit A is the correct and complete Exhibit A to the Patent Assignment.

NOW THEREFORE, the undersigned hereby acknowledge and agree as follows:

1. The attached Exhibit A is the correct and complete Exhibit A to the Patent Assignment.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, Assignors have caused this Acknowledgment to be executed by their duly authorized representatives as of the day and year first above written.

TEGAL CORPORATION

*Thomas R. Mika*

Name: Thomas R. Mika

Title: President and Chief Executive Officer

SPUTTERED FILMS, INC.

*Thomas R. Mika*

Name: Thomas R. Mika

Title: President and Chief Executive Officer

ACKNOWLEDGEMENT:

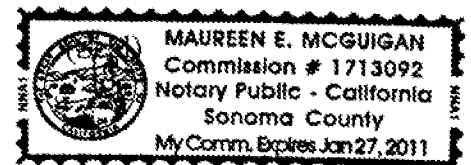
STATE OF CALIFORNIA )  
 ) SS:  
COUNTY OF )

On April 23, 2010 before me Maureen E. McGuigan, personally appeared Thomas R. Mika who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature *Maureen E. McGuigan*



SIGNATURE PAGE TO ACKNOWLEDGMENT

IN WITNESS WHEREOF, the Parties hereto have duly executed this Amendment as of the day and year first above written.

**TEGAL CORPORATION**

By:   
Name: Thomas R. Mika

Title: President and Chief Executive Officer

**SPUTTERED FILMS, INC.**

By:   
Name: Thomas R. Mika

Title: President and Chief Executive Officer

**OEG-TEG, LLC**

By: \_\_\_\_\_  
Name: Wayne Jeveli

Title: Manager

**OEM GROUP, INC.**

By: \_\_\_\_\_  
Name: Wayne Jeveli

Title: President

[SIGNATURE PAGE TO FIRST AMENDMENT TO ASSET PURCHASE AGREEMENT]

Schedule 2.1.1(e)  
Transferred Intellectual Property

[illegible]

## EXHIBIT A TO THE PATENT ASSIGNMENT

Schedule 2.1 1(e)  
Transferred Intellectual Property

## TRANSFERRED PENDING PATENTS AND PATENT APPLICATIONS

Docket No.	Description	Country	App. Date	App. No.	Title
TEGL-01008EP0	HfRe source	EP	1/23/1997	97807537.1	PLASMA ETCH REACTOR AND METHOD
TEGL-01009CN1	HfRe for emerging films	CN	1/23/1997	200410030869.4	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009EP0	HfRe for emerging films	EP	1/23/1997	97803810.4	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009JP0	HfRe for emerging films	JP	1/23/1997	10-504082	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01021EP0	HfRe/emerging film etch	EP	1/23/1997	97803803.4	METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER
TEGL-01021JP0	HfRe/emerging film etch	JP	1/23/1997	10-504081	IMPROVED METHOD & APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER WITH FEATURES HAVING VERTICAL SIDEWALLS
TEGL-01092EP0	Heated/fluorinated HfRe surfaces	EP	11/21/2000	980631.9	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01092JP0	Heated/fluorinated HfRe surfaces	JP	11/21/2000	2001-542603	IMPROVED REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01092US2	Heated/fluorinated HfRe surfaces	US	9/03/00	12/203,022	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01209EP0	Reactive sputtered SiNx	EP	5/12/2004	4752185	DEPOSITION APPARATUS AND METHOD
TEGL-01209JP0	Reactive sputtered SiNx	JP	5/12/2004	2006-533061	DEPOSITION APPARATUS AND METHOD
TEGL-01215JP0	Degassed/etched Cluster tool	JP	7/2/2001	2002-507709	DUAL DEGAUSSION LOADLOCK CLUSTER TOOL
TEGL-01243US0	Magnetron w/Adjustable Target	US	3/21/2002	10/371,692; 6,000,401; 6,050,521	MAGNETRON WITH ADJUSTABLE TARGET POSITIONING
TEGL-0021US0	High adhesive backside metallization	US	9/27/2007	US 11,693,046 (2008003611)	HIGH-ADHESIVE BACKSIDE METALLIZATION
TEGL-0004a	Stress adjustment in reactive sputtering	US	3/03/2003	20030240302 US 6,103,948	STRESS ADJUSTMENT IN REACTIVE SPUTTERING
TEGL-0004b	Stress adjustment in reactive sputtering	US	3/25/2003	30090242366 US 6,103,949	STRESS ADJUSTMENT IN REACTIVE SPUTTERING
TEGL-0005	Stress control in reactive sputtering	US	5/11/2003 PROV	US 6,103,944 12/411,289	Control of crystal orientation and stress in wafer deposited thin films
TEGL-0006	SiO <sub>2</sub> PVD patent (Volery)	US	3/25/2006	US20060240365 6,116,084	Sputter deposition of carrier transfer films with low TCR
TEGL-01172JP0	Stop on Alumina1	JP	9/9/2006	2007-531406	SYSTEM AND METHOD FOR PROCESSING A WAFER INCLUDING STOP-ON-ALUMINUM PROCESSING
TEGL-01247JP0	Stop on Alumina2	JP	3/16/2007	2009-500499	DRY ETCH STOP PROCESS FOR ELIMINATING ELECTRICAL SHORTING IN MRAM DEVICE STRUCTURES
TEGL-01247US2	Stop on Alumina2	US	12/14/2009	US20100322090	DRY ETCH STOP PROCESS FOR ELIMINATING ELECTRICAL SHORTING IN MRAM DEVICE STRUCTURES



**PATENT ASSIGNMENT**

**THIS PATENT ASSIGNMENT** (this "Assignment") is made and entered into as of this 19th day of March, 2010 ("Effective Date") by and among Tegal Corporation, a Delaware corporation ("Tegal"), Sputtered Films, Inc., a California corporation (together with Tegal, "Assignors") and OEG-TEG, LLC, an Arizona limited liability corporation ("Assignee"). Capitalized terms not otherwise defined herein shall have the meanings assigned to such terms in the Purchase Agreement (as defined below).

W I T N E S S E T H:

WHEREAS, Assignors and Assignee are parties to that certain Asset Purchase Agreement, dated March 19, 2010 (the "Purchase Agreement"), pursuant to which Assignee has acquired all of Assignors' right, title and interest in and to certain patents and patent applications as listed on Exhibit A hereto (the "Assigned Patents");

WHEREAS, to effect the transfer of the Assigned Patents as contemplated in the Purchase Agreement, Assignors and Assignee desire to enter into this Assignment;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors and Assignee each hereby agree as follows:

1. Assignment. Assignors hereby sell, assign, transfer, convey and deliver to Assignee and its successors and assigns, and Assignee hereby purchases and accepts from Assignors, all of Assignors' right, title and interest in, to and under the Assigned Patents, and to any continuations, continuations-in-part, divisionals, renewals, substitutes, reexaminations and reissues thereof and foreign counterparts thereto, and all patents issuing therefrom, together with all priority rights under any international conventions and treaties, and the right to sue and recover damages for future or past infringements of the Assigned Patents and to fully and entirely stand in the place of Assignors in all matters related thereto.

2. Further Assurances. Assignors agree to execute and deliver such other documents and to take all such other actions as Assignee, its successors and assigns may reasonably request to effect the terms of this Assignment and to execute and deliver any and all affidavits, testimonies, declarations, oaths and other documentation as may be reasonably required to effect the terms of this Assignment. Assignee, or its successor or assign, as the case may be, shall be responsible for all costs incurred by Assignors in executing and delivering any of the foregoing.

3. Authorization. Assignors hereby authorize and request the Commissioner of Patents and Trademarks of the United States, and, in the case of any patent applications filed with any office of any country or countries foreign to the United States, any officer of such country whose duty it is to issue patents or other evidence or forms of intellectual property protection or applications as aforesaid, to issue the same to Assignee and its successors, assigns and other legal representatives in accordance with the terms of this Assignment.

4. Miscellaneous. This Assignment may not be supplemented, altered or modified in any manner except by a writing signed by all parties hereto. The failure of any party to enforce any terms or provisions of this Assignment shall not waive any of its rights under such terms or provisions. This Assignment shall bind and inure to the benefit of the respective parties and their assigns, transferees and successors. This Assignment and any amendments hereto may be executed in one or more counterparts, each of which shall be deemed an original but all of which together will constitute one and the same instrument.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, Assignors have caused this Assignment to be executed by their duly authorized representatives as of the Effective Date.

TEGAL CORPORATION

*[Signature]*

Name: Thomas R. Mika

Title: President and Chief Executive Officer

SPUTTERED FILMS, INC.

*[Signature]*

Name: Thomas R. Mika

Title: President and Chief Executive Officer

ACKNOWLEDGEMENT:

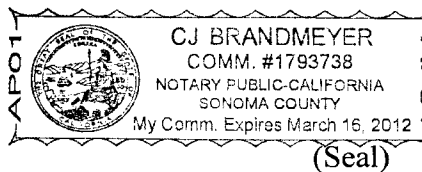
STATE OF CALIFORNIA )  
COUNTY OF Sonoma ) SS:

On 3/19/10 before me *CJ Brandmeyer, Notary Public*, personally appeared THOMAS R. MIKA who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature *[Signature]*



[Signature Page to Patent Assignment]

IN WITNESS WHEREOF, Assignee has caused this Assignment to be executed by its duly authorized representatives as of the Effective Date.

OEG-TEG, LLC

Wayne Jeveli

Name: Wayne Jeveli

Title: Manager

ACKNOWLEDGEMENT:

STATE OF CALIFORNIA )  
COUNTY OF Sonoma ) SS:

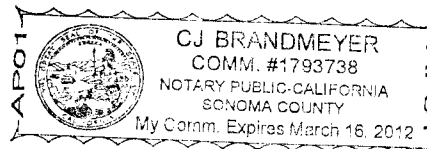
On 3/19/10 before me CJ Brandmeyer, Notary Public, personally appeared WAYNE JEVELI who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Signature CJ Brandmeyer

(Seal)



**EXHIBIT A**

## EXHIBIT A TO THE PATENT ASSIGNMENT AGREEMENT

Schedule 2.1.1(d)  
Transferred Intellectual Property

## ISSUED PATENTS TO BE TRANSFERRED

Docket No.	Description	Pat. No.	Expire date	Title
TEGL-01003CN0	Rinse/Strip/Rinse	84001	3/28/2016	INTEGRATED SEMICONDUCTOR WAFER PROCESSING SYSTEM
TEGL-01003EP0	Rinse/Strip/Rinse	826231	3/28/2016	INTEGRATED SEMICONDUCTOR WAFER PROCESSING SYSTEM
TEGL-01003FR0	Rinse/Strip/Rinse	826231	3/28/2016	INTEGRATED SEMICONDUCTOR WAFER PROCESSING SYSTEM
TEGL-01003JP0	Rinse/Strip/Rinse	3686678	3/28/2016	INTEGRATED SEMICONDUCTOR WAFER PROCESSING SYSTEM
TEGL-01003KR0	Rinse/Strip/Rinse	441637	3/28/2016	INTEGRATED SEMICONDUCTOR WAFER PROCESSING SYSTEM
TEGL-01003US0	Rinse/Strip/Rinse	5,672,239	5/10/2015	INTEGRATED SEMICONDUCTOR WAFER PROCESSING SYSTEM
TEGL-01004US0	ICP Stripper Source	5,985,089	11/16/2016	PLASMA ETCH SYSTEM
TEGL-01004US1	ICP Stripper Source	5,958,139	5/25/2015	PLASMA ETCH SYSTEM
TEGL-01004US2	ICP Stripper Source	5,120,610	5/25/2015	PLASMA ETCH SYSTEM
TEGL-01008CN0	HRe source	ZL97197274.5	1/23/2017	PLASMA ETCH REACTOR AND METHOD
TEGL-01008KR0	HRe source	453538	1/23/2017	PLASMA ETCH REACTOR AND METHOD
TEGL-01008US5	HRe source	5,500,314	7/3/2016	PLASMA ETCH REACTOR AND METHOD
TEGL-01008US6	HRe source	5,620,335	7/3/2016	PLASMA ETCH REACTOR AND METHOD
TEGL-01008US7	HRe source	5,354,240	9/11/2018	PLASMA ETCH REACTOR AND METHOD
TEGL-01008US8	HRe source	5,905,969	3/5/2017	PLASMA ETCH REACTOR AND METHOD
TEGL-01008US9	HRe source	7,223,699	7/3/2016	PLASMA ETCH REACTOR AND METHOD
TEGL-01009CN0	HRe for emerging films	ZL97197108.0	1/23/2017	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009CN2	HRe for emerging films	200410003858.X	1/23/2017	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009KR0	HRe for emerging films	528733	1/23/2017	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009US0	HRe for emerging films	5,048,435	7/3/2016	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009US1	HRe for emerging films	5,419,449	7/3/2016	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009US2	HRe for emerging films	5,190,495	7/3/2016	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01021CN0	HRe/Emingng film etch	ZL97197232.X	1/23/2017	IMPROVED METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER WITH FEATURES HAVING VERTICAL SIDEWALLS
TEGL-01021KR0	HRe/Emingng film etch	537231	1/23/2017	METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER
TEGL-01021US0	HRe/Emingng film etch	6,127,277	7/3/2016	METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER WITH FEATURES HAVING VERTICAL SIDEWALLS
TEGL-01021US1	HRe/Emingng film etch	6,492,280	11/1/2016	METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER WITH FEATURES HAVING VERTICAL SIDEWALLS
TEGL-01071US0	Wafer T Control	6,046,116	11/19/2017	A METHOD FOR MINIMIZING THE CRITICAL DIMENSION GROWTH OF A FEATURE ON A SEMICONDUCTOR WAFER
TEGL-01071US3	Wafer T Control	5,774,045	9/28/2018	METHOD FOR MINIMIZING THE CRITICAL DIMENSION GROWTH OF A FEATURE ON A SEMICONDUCTOR WAFER
TEGL-01073CN0	ICP deposition shield	123764	12/1/2018	PLASMA REACTOR WITH A DEPOSITION SHIELD
TEGL-01073US1	ICP deposition shield	6,006,694	12/5/2017	PLASMA REACTOR WITH A DEPOSITION SHIELD
TEGL-01073US2	ICP deposition shield	5,360,686	12/5/2017	PLASMA REACTOR WITH A DEPOSITION SHIELD
TEGL-01073US3	ICP deposition shield	5,173,674	12/5/2017	PLASMA REACTOR WITH A DEPOSITION SHIELD
TEGL-01073US4	ICP deposition shield	5,170,431	12/5/2017	PLASMA REACTOR WITH A DEPOSITION SHIELD
TEGL-01073US5	ICP deposition shield	5,521,081	12/5/2017	DEPOSITION SHIELD FOR A PLASMA REACTOR
TEGL-01082CN0	Oxidized HM during Etch	ZL9903212.3	1/5/2019	METHOD FOR USING A HARD MASK FOR CRITICAL DIMENSION GROWTH CONTAINMENT
TEGL-01082KR0	Oxidized HM during Etch	538639	1/5/2019	METHOD FOR USING A HARD MASK FOR CRITICAL DIMENSION GROWTH CONTAINMENT
TEGL-01082US1	Oxidized HM during Etch	6,287,975	1/20/2018	METHOD FOR USING A HARD MASK FOR CRITICAL DIMENSION GROWTH CONTAINMENT
TEGL-01082US2	Oxidized HM during Etch	5,958,285	1/20/2018	METHOD FOR USING A HARD MASK FOR CRITICAL DIMENSION GROWTH CONTAINMENT
TEGL-01082US3	Oxidized HM during Etch	5,951,820	10/19/2020	METHOD FOR USING A HARD MASK FOR CRITICAL DIMENSION GROWTH CONTAINMENT

PATENT

REEL: 024551 FRAME: 0037

EXHIBIT A TO THE PATENT ASSIGNMENT AGREEMENT

Schedule 2.1.1(d)  
Transferred Intellectual Property

ISSUED PATENTS TO BE TRANSFERRED

Docket No.	Description	Pat. No.	Expire date	Title
TEGL-01083US1	ESC microarc elimination	5,345,428	8/17/2018	METHOD AND APPARATUS FOR MINIMIZING SEMICONDUCTOR WAFER ARCING DURING SEMICONDUCTOR WAFER PROCESSING
TEGL-01083US2	ESC microarc elimination	5,405,925	8/17/2018	METHOD AND APPARATUS FOR MINIMIZING SEMICONDUCTOR WAFER ARCING DURING SEMICONDUCTOR WAFER PROCESSING
TEGL-01092US1	Heated/Textured HfRe surfaces	7,439,188	12/2/2019	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01102US0	CoSi Etch process	5,485,059	12/3/2019	COBALT SILICIDE ETCH PROCESS AND APPARATUS
TEGL-01203US0	Backside adhesion layer	7,208,386	1/16/2022	PERMANENT ADHERENCE OF THE BACK END OF A WAFER TO AN ELECTRICAL COMPONENT OR SUB-ASSEMBLY
TEGL-01209US0	Reactive sputtered SiNx	7,179,350	2/18/2025	REACTIVE SPUTTERING OF SILICON NITRIDE FILMS BY RF SUPPORTED DC MAGNETRON
TEGL-01210US0	Crack effect elimination	6,086,947	10/10/2016	METHOD OF DEPOSITING MATERIALS ON A WAFER TO ELIMINATE THE EFFECT OF CRACKS IN THE DEPOSITION
TEGL-01211US0	Flat Magnetron	6,783,638	10/30/2021	FLAT MAGNETRON
TEGL-01212US0	Surface etching system and method	7,457,598	3/10/2026	SYSTEM FOR, AND METHOD OF, ETCHING A SURFACE ON A WAFER
TEGL-01212US1	Surface etching system and method	7,270,729	2/20/2023	SYSTEM FOR, AND METHOD OF, ETCHING A SURFACE ON A WAFER
TEGL-01213US0	PVD Apparatus	5,605,199	10/18/2016	APPARATUS FOR, AND METHOD OF, DEPOSITING A FILM ON A SUBSTRATE
TEGL-01214US0	Hydrocarbon removal system and method	5,914,017	5/22/2015	APPARATUS FOR, AND METHOD OF, REMOVING HYDROCARBONS FROM THE SURFACE OF A SUBSTRATE
TEGL-01218EP0	Degas/Loadlock Cluster tool	150,940	7/2/2021	DUAL DEGAS/COOL LOADLOCK CLUSTER TOOL
TEGL-01218US0	Degas/Loadlock Cluster tool	9,235,556	7/3/2020	DUAL DEGAS/COOL LOADLOCK CLUSTER TOOL
TEGL-01218US1	Degas/Loadlock Cluster tool	6,552,141	10/6/2020	DUAL DEGAS/COOL LOADLOCK CLUSTER TOOL
TEGL-01219US0	Cluster tool with hollow cathode array	8,830,664	10/10/2022	CLUSTER TOOL WITH A HOLLOW CATHODE ARRAY
TEGL-01242US0	Magnetron w/controlled dc power	9,924,653	3/8/2023	MAGNETRON WITH CONTROLLED DC POWER

EXHIBIT A TO THE PATENT ASSIGNMENT

Schedule 2.1.(e)  
Transferred Intellectual Property

TRANSFERRED PENDING PATENTS AND PATENT APPLICATIONS

Docket No.	Description	Counth	App. Date	App. No.	Title
TEGL-01008EP0	HRe source	EP	1/23/1997	97907537.1	PLASMA ETCH REACTOR AND METHOD
TEGL-01009CN1	HRe for emerging films	CN	1/23/1997	200410003859.4	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009EP0	HRe for emerging films	EP	1/23/1997	97903910.4	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01009JP0	HRe for emerging films	JP	1/23/1997	10-504082	PLASMA ETCH REACTOR AND METHOD FOR EMERGING FILMS
TEGL-01021EP0	HRe/Emerging film etch	EP	1/23/1997	97903905.4	METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER
					IMPROVED METHOD & APPARATUS FOR ETCHING A SEMICONDUCTOR WAFER WITH FEATURES HAVING VERTICAL SIDEWALLS
TEGL-01021JP0	HRe/Emerging film etch	JP	1/23/1997	10-504081	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01092EP0	Heated/Textured HRe surfaces	EP	11/21/2000	980631.6	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01092JP0	Heated/Textured HRe surfaces	JP	11/21/2000	2001-542603	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01092US2	Heated/Textured HRe surfaces	US	9/2/2008	12/203,022	REACTOR WITH HEATED AND TEXTURED ELECTRODES AND SURFACES
TEGL-01203EP0	Reactive sputtered SiNx	EP	5/12/2004	4752195	DEPOSITION APPARATUS AND METHOD
TEGL-01203JP0	Reactive sputtered SiNx	JP	5/12/2004	2006-539861	DEPOSITION APPARATUS AND METHOD
TEGL-01213JP0	Degassed Loadlock Cluster Tool	JP	7/2/2001	2002-507709	DUAL DEGAS/COOL LOADLOCK CLUSTER TOOL
TEGL-01242US0	Magnetron with adjustable Target	US	2/21/2003	10/371,862; 12/094,016; 952,1	MAGNETRON WITH ADJUSTABLE TARGET POSITIONING
TEGL-0202US0	High adhesive backside metallization	US	9/27/2007	US 11/553,046 (DUSM183611)	HIGH-ADHESIVE BACKSIDE METALLIZATION
Tegals004a	Stress adjustment in reactive sputtering	US	3/25/2009	20090242382	STRESS ADJUSTMENT IN REACTIVE SPUTTERING
Tegals004b	Stress adjustment in reactive sputtering	US	3/25/2009	20090242388	STRESS ADJUSTMENT IN REACTIVE SPUTTERING
Tegals005	Stress control in reactive sputtering	US	5/11/2009 PPOV	US 61/039,349	Control of crystal orientation and stress in sputter deposited thin films
Tegals008	SiCr PVD patent (Valley)	US	3/25/2009	US20090246365	Sputter deposition of cermet resistor films with low TCR
					SYSTEM AND METHOD FOR PROCESSING A WAFER INCLUDING STOP-ON-ALUMINUM PROCESSING
TEGL-01172JP0	Stop on Alumina1	JP	9/9/2005	2007-531406	DRY ETCH STOP PROCESS FOR ELIMINATING ELECTRICAL SHORTING IN MRAM DEVICE STRUCTURES
TEGL-01247JP0	Stop on Alumina2	JP	3/16/2007		DRY ETCH STOP PROCESS FOR ELIMINATING ELECTRICAL SHORTING IN MRAM DEVICE STRUCTURES
TEGL-01247US2	Stop on Alumina2	US	12/14/2009		DRY ETCH STOP PROCESS FOR ELIMINATING ELECTRICAL SHORTING IN MRAM DEVICE STRUCTURES